

LMPBSS84WX5F 60V P-Channel MOSFET
Features

- -60V/-0.13A, $R_{DS(ON)} < 10\Omega @ V_{GS} = -5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-323 package design

Product Description

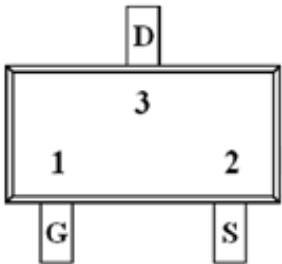
LMPBSS84WX5F, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

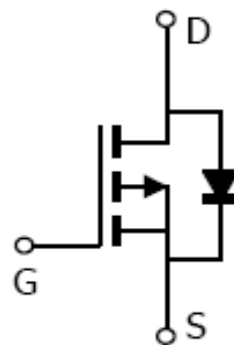
These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

Applications

- DC to DC Converter
- Cellular & PCMCIA Card
- Power Management in Portable and Battery etc
- Cordless Telephone

Pin Configuration

LMPBSS84WX5F (SOT-323)	
	
PIN	Description
1	Gate
2	Source
3	Drain



Ordering Information

Ordering Information					
Part Number	P/N	PKG code	Pb Free code	Package	Quantity
LMPBSS84WX5F	LMPBSS84W	X5	F	SOT-323	3000

Marking Information

Marking Information		
Part Marking	Part Number	LFC code
PD	P	D

Absolute Maximum Ratings

(T_C=25°C Unless otherwise noted)

Symbol	Parameter	Typical	Unit
V _{DSS}	Drain-Source Voltage	-60	V
V _{GSS}	Gate-Source Voltage	±20	V
I _D	Continuous Drain Current(T _A =25°C)	-130	mA
I _{DM}	Pulsed Drain Current (tp≤10us)	-520	mA
I _S	Continuous Current	-0.13	A
P _D	Power Dissipation (T _A =25°C)	225	mW
T _J	Operating Junction Temperature	-55 to 150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
R _{θJA}	Maximax Junction to Ambient	556	°C/ W

Note 1: Pulse Test: PW≤300us, Duty Cycle≤2%.

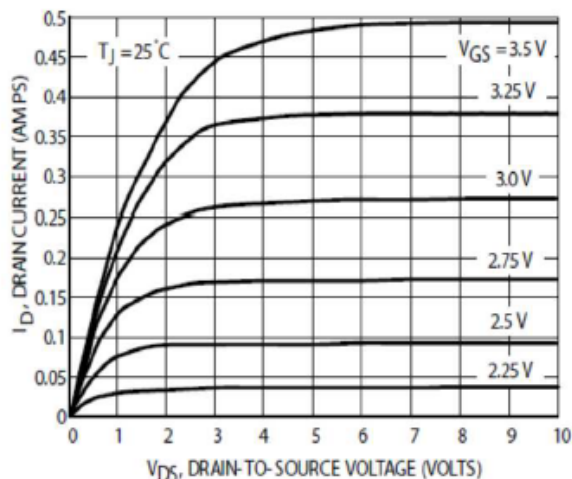
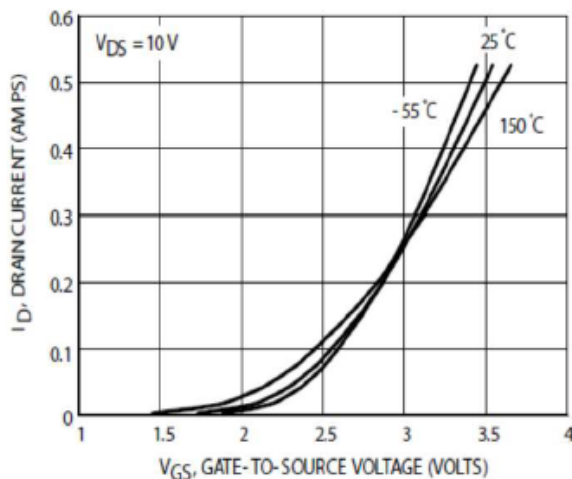
2: Switching Time is Essentially Independent of Operating Temperature.

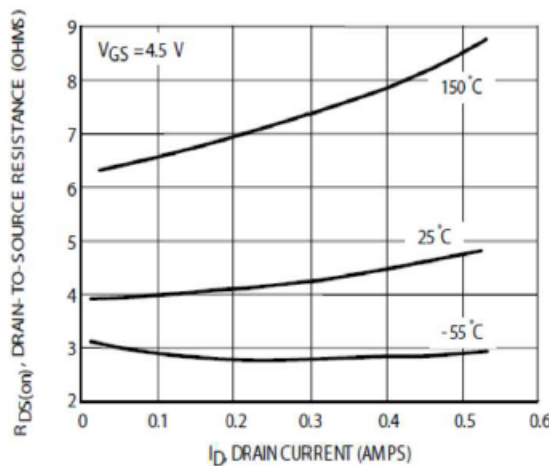
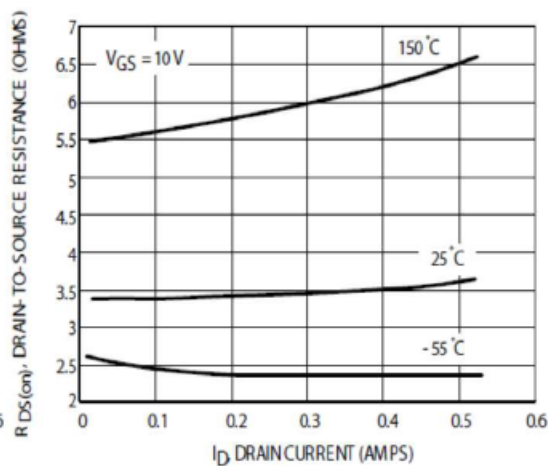
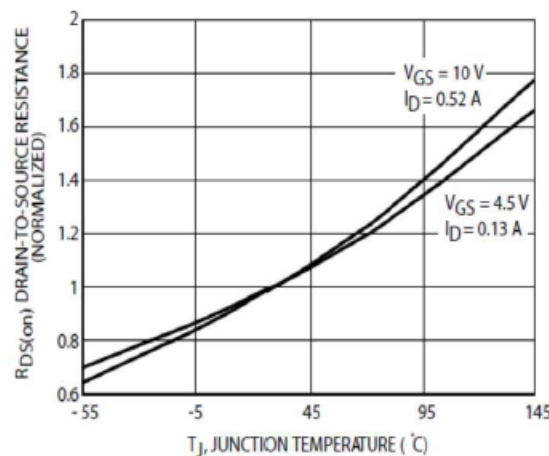
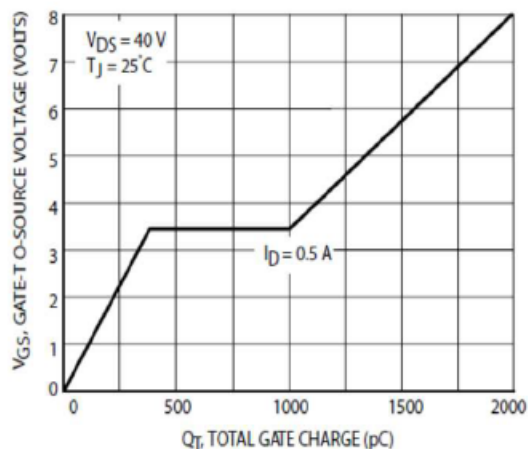
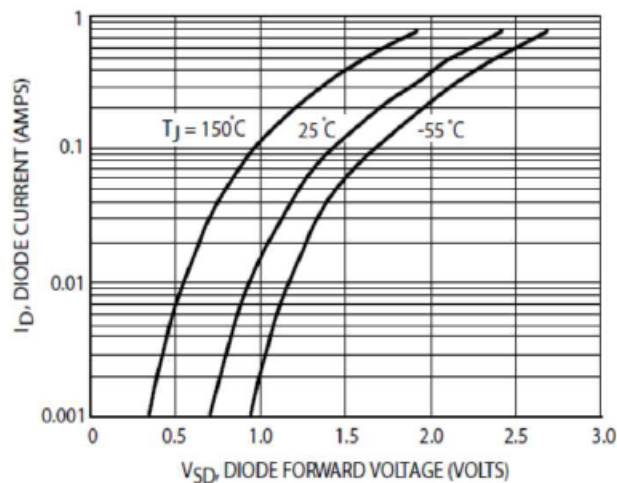
Electrical Characteristics

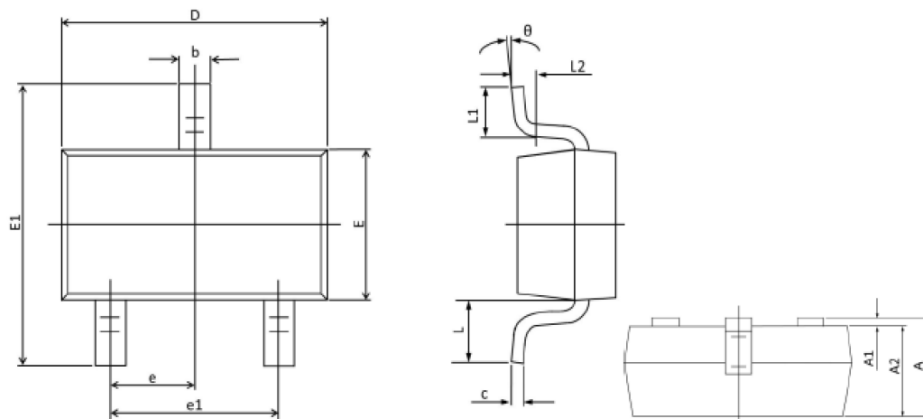
($T_C=25^{\circ}\text{C}$ Unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-60			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-1.0mA	-0.8		-2.0	
I _{GSS}	Gate-Source Leakage Current	V _{DS} =0V, V _{GS} =±20V			±60	uA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -25V, V _{GS} =0V			-0.1	uA
		V _{DS} = -50V, V _{GS} =0V			-15	
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =-5V, I _D =-100mA			10	Ω
g _{fs}	Forward Transconductance	V _{DS} =-25V, I _D =-100mA, f=1.0KHz	50			mS
V _{SD}	Forward Voltage			-2.5		V
Dynamic						
C _{iss}	Input Capacitance	V _{DS} =-5V, V _{GS} =0V, f=1MHz		30		pF
C _{oss}	Output Capacitance			10		
C _{rss}	Reverse Transfer Capacitance			5.0		
Q _G	Gate Charge			6		nC
t _{d(on)}	Turn-On Time	V _{DD} =-15V, R _L =50Ω , I _D =-2.5A		25		ns
t _r				1.0		
t _{d(off)}	Turn-Off Time			16		
t _f				8.0		

Typical Performance Characteristics



Typical Performance Characteristics(continue)

On-Resistance versus Drain Current

On-Resistance versus Drain Current

On-Resistance Variation with Temperature

Gate Charge

Body Diode Forward Voltage

Package Dimension:
SOT-323


Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.800	1.100	0.031	0.043
A1	0.000	0.100	0.000	0.004
A2	0.800	1.000	0.031	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.250	0.003	0.010
D	1.800	2.200	0.071	0.087
E	1.150	1.350	0.045	0.053
E1	1.800	2.450	0.071	0.096
e	0.650 (BSC)		0.026 (BSC)	
e1	1.200	1.40	0.047	0.055
L	0.525 (REF)		0.021 (REF)	
L1	0.150	0.460	0.006	0.018
L2	0.000	0.200	0.000	0.008
θ	0 °	8 °	0 °	8 °

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